

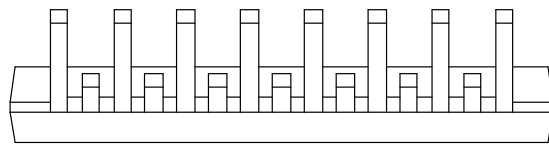
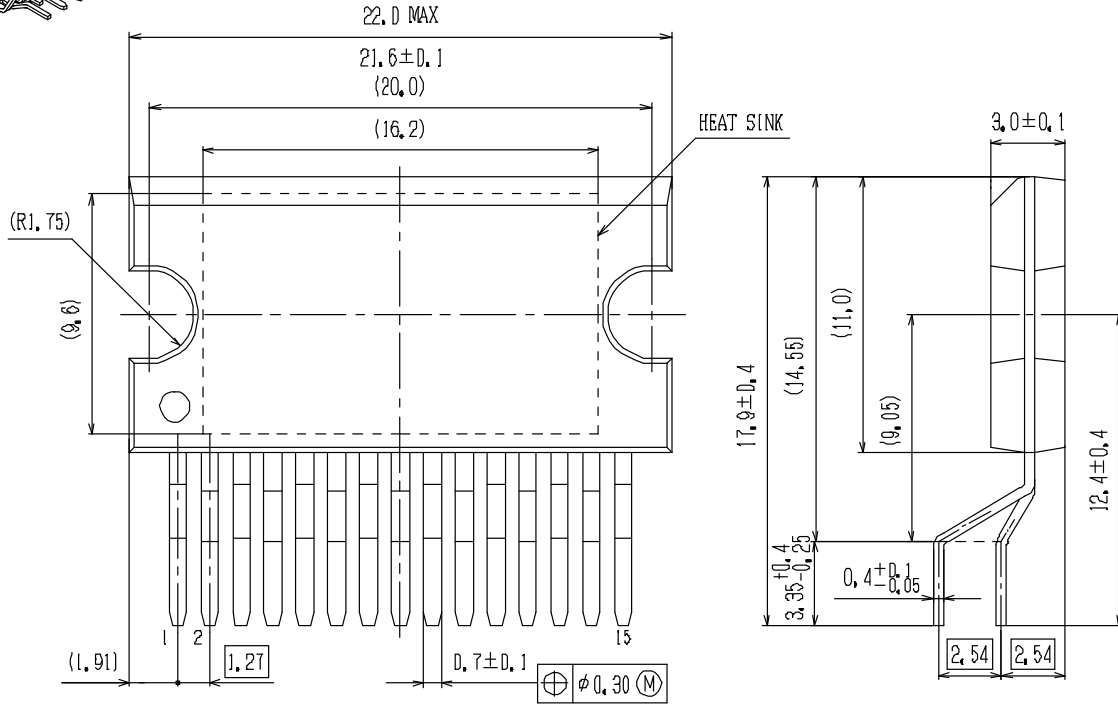
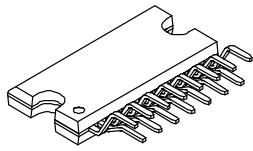
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

ON Semiconductor®

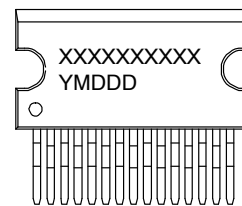


HZIP15J
CASE 945AC
ISSUE A

DATE 24 OCT 2013



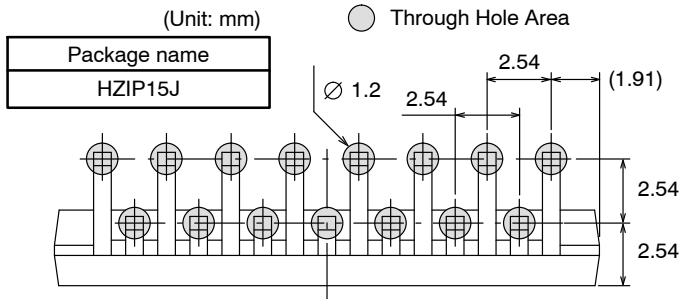
GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON65475E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	HZIP15J	PAGE 1 OF 2

